



## SCOPE OF ACCREDITATION

### Electronics

**Minco Products Inc**  
7300 Commerce Ln NE  
Minneapolis, MN 55432-3177

This certificate expiration is updated based on periodic audits. The current expiration date and scope of accreditation are listed at: [www.eAuditNet.com](http://www.eAuditNet.com) - Online QML (Qualified Manufacturer Listing).

In recognition of the successful completion of the PRI evaluation process, accreditation is granted to this facility to perform the following:

### **AC7119 Rev F - Nadcap Audit Criteria for Electronics Printed Boards**

- 06– CAD/CAM Data
- 07.1– Material Control: General
- 07.2– Material Control: PrePreg
- 08.1b– Imaging – Photoprocess – Laser Direct Imaging (LDI)
- 08.2.1– DES – Developing Photoimageable Resist
- 08.2.2– DES – Copper Etching of Inner Layers and Outer Layers
- 08.2.3– DES – Stripping of Resist Film and Etch–Resist Plating
- 08.2– Imaging – Layer Develop – Etch – Strip (DES)
- 08.3 – Etched Image Inspection (Manual or AOI)
- 09.1– Permanent Solder Mask: Solder Mask Application
- 09.2– Permanent Solder Mask: Solder Mask Exposing
- 09.3– Permanent Solder Mask: Solder Mask Develop and Cure
- 09– Permanent Solder Mask
- 10– Oxide Coating / Oxide Replacement Coating
- 11– Material Lay–Up and Lamination
- 12.1– Drilling: Mechanical Drilling
- 12.2– Drilling: Laser Drilling – In House
- 12.4– Post–Drill Cleaning and Etchback
- 13.1– Copper Plating: Electroless Copper/Direct Metallization
- 13.2– Copper Plating: Electroplated Copper
- 14.1– Final Finishes: Hot Air Solder Leveling (HASL)
- 14.2– Final Finishes: Fused Tin Lead
- 14.4– Final Finishes: Electroplated Final Finishes
- 15– Legend and Marking

- 16– Routing and Machining
- 17– Electrical Test – Functional
- 18– X–Ray Fluorescence (XRF)
- 19– Mircosection Sample Selection, Preparation, and Inspection
- 20– Structural Integrity
- 21– Materials Lab
- 22– Chemistry Lab
- 24– Final Validation
- 25– Packaging

**AC7119/2 - Nadcap Audit Criteria for Electronics Flexible and Rigid-Flexible Printed Boards**

- 04– Laminate Material
- 05– Material
- 06– Testing
- 07– Environment Requirements
- 08– Special Requirements
- 09– Packaging
- 10– Contouring
- 13– Final Validation